

This Page Is Inserted by IFW Operations
and is not a part of the Official Record

BEST AVAILABLE IMAGES

Defective images within this document are accurate representations of the original documents submitted by the applicant.

Defects in the images may include (but are not limited to):

- BLACK BORDERS
- TEXT CUT OFF AT TOP, BOTTOM OR SIDES
- FADED TEXT
- ILLEGIBLE TEXT
- SKEWED/SLANTED IMAGES
- COLORED PHOTOS
- BLACK OR VERY BLACK AND WHITE DARK PHOTOS
- GRAY SCALE DOCUMENTS

IMAGES ARE BEST AVAILABLE COPY.

**As rescanning documents *will not* correct images,
please do not report the images to the
Problem Image Mailbox.**

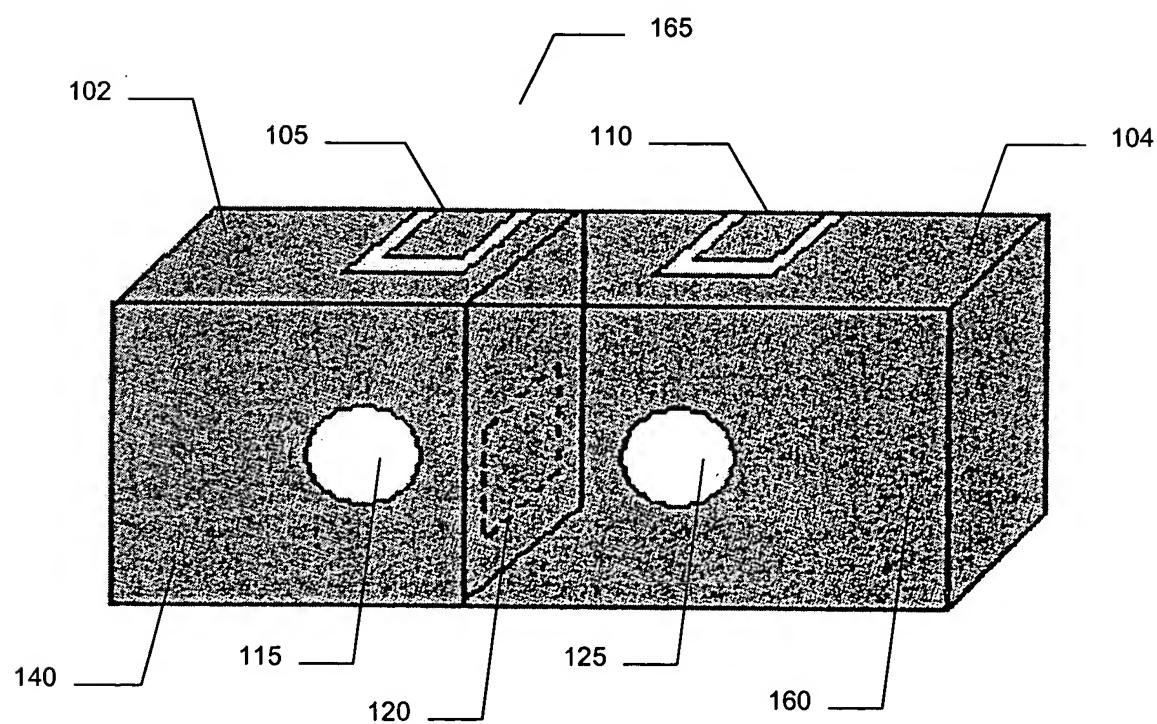
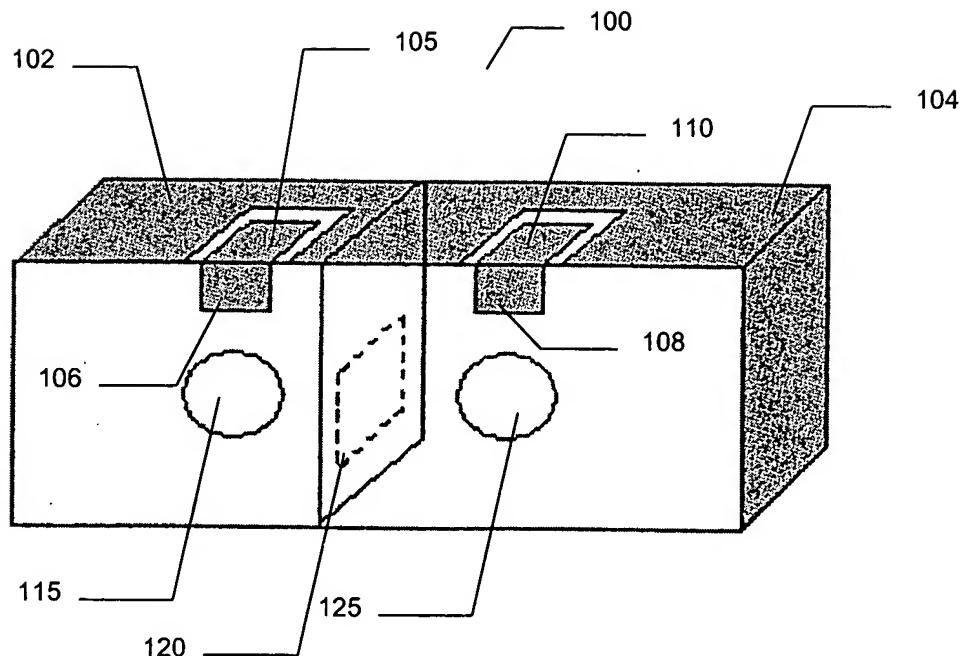


FIGURE 1

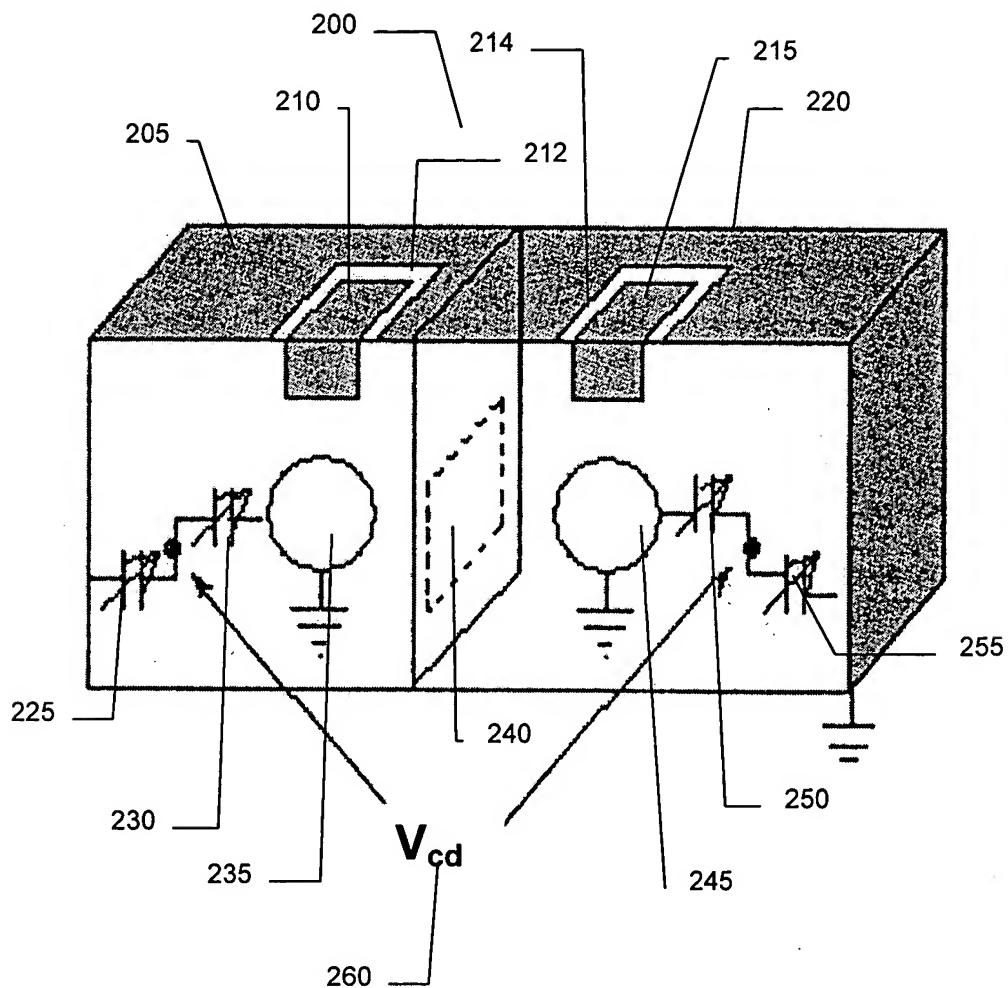


FIGURE 2

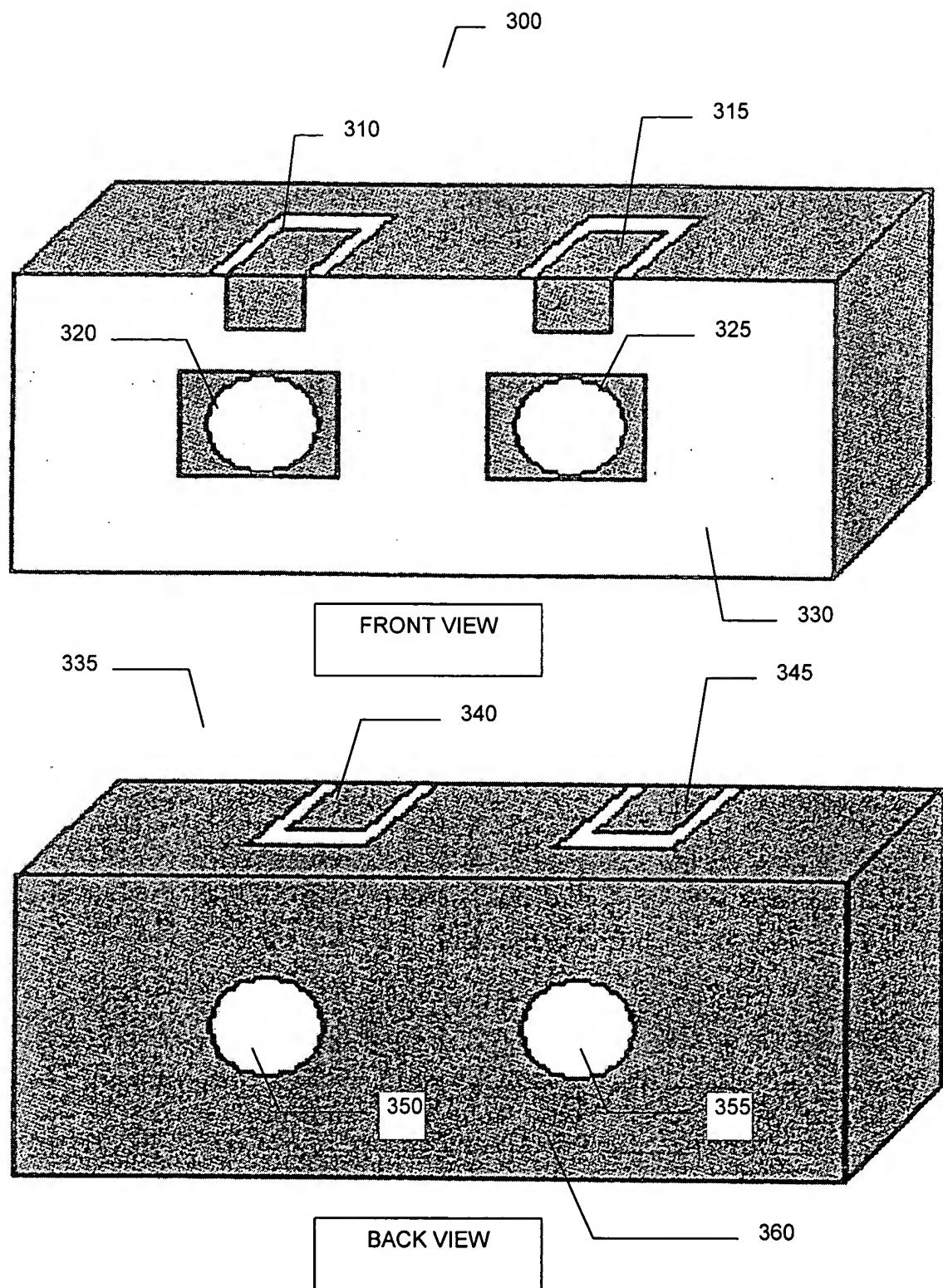


FIGURE 3

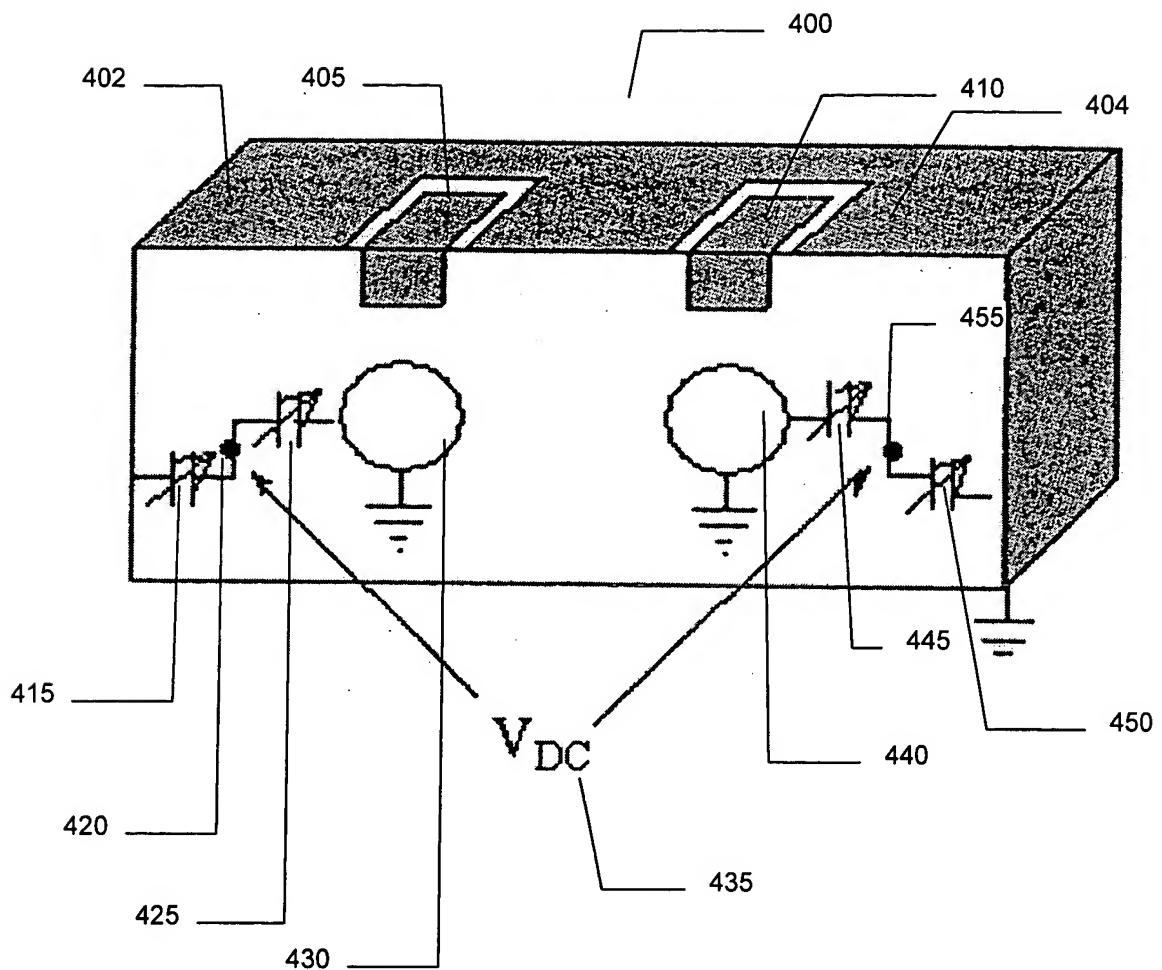


FIGURE 4

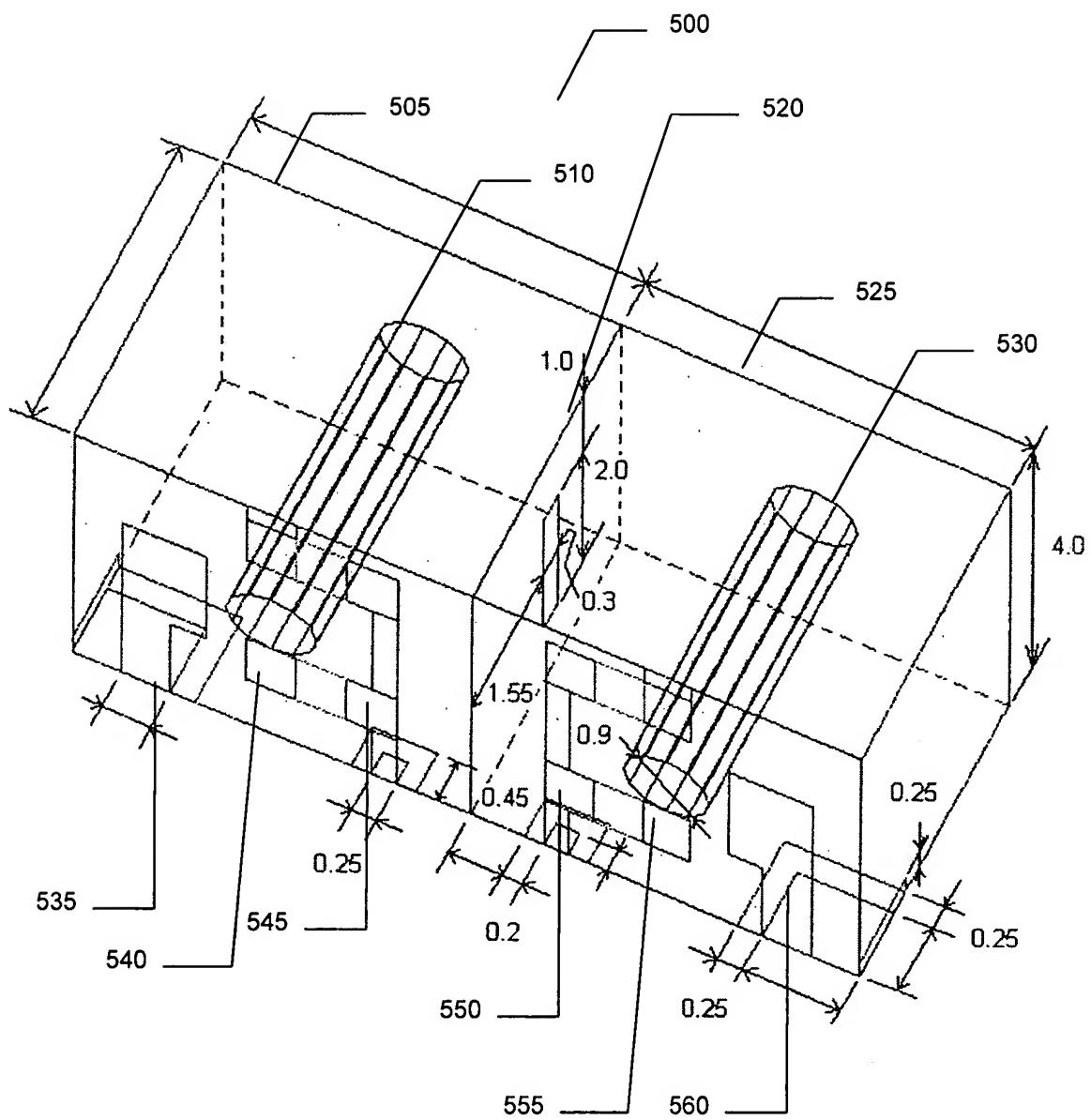


FIGURE 5

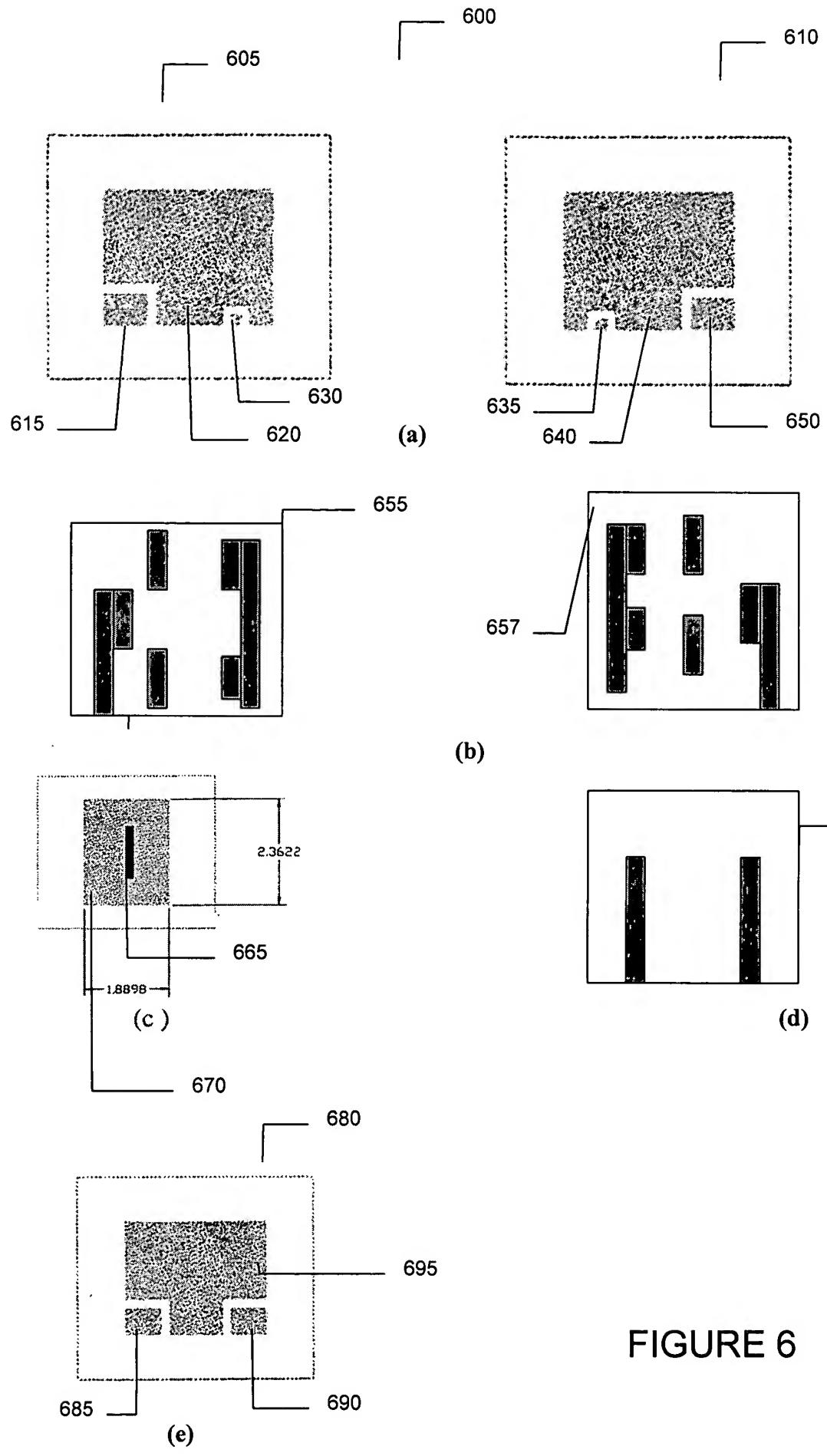


FIGURE 6

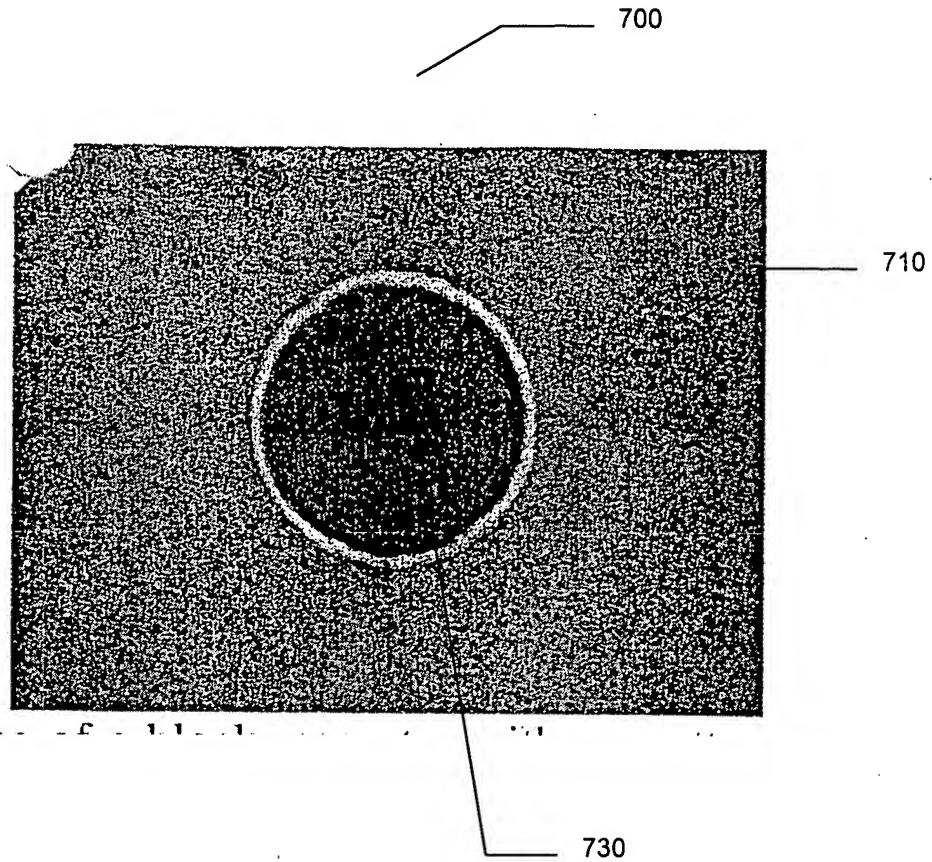


FIGURE 7

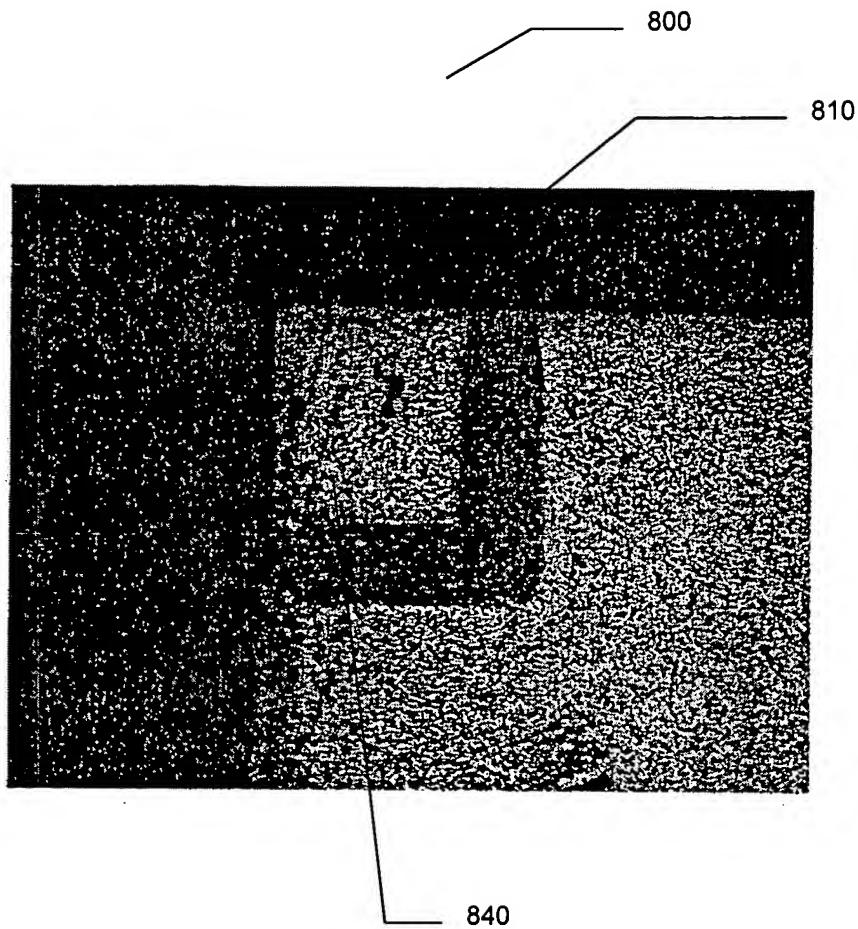


FIGURE 8

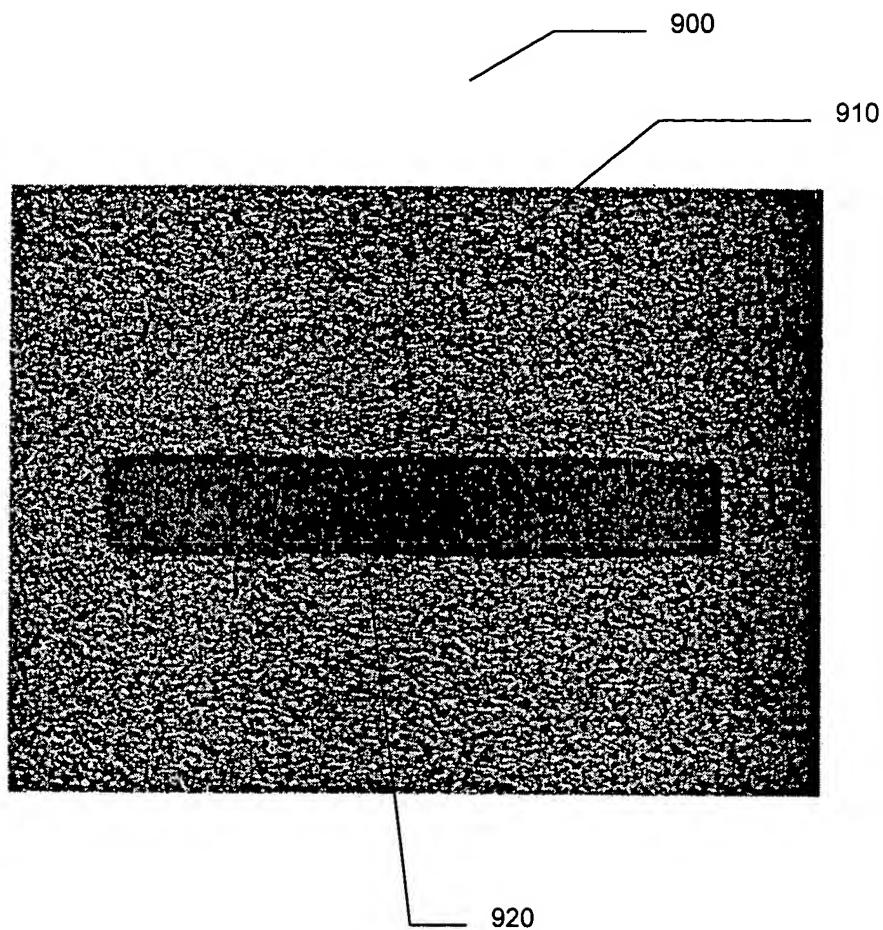


FIGURE 9

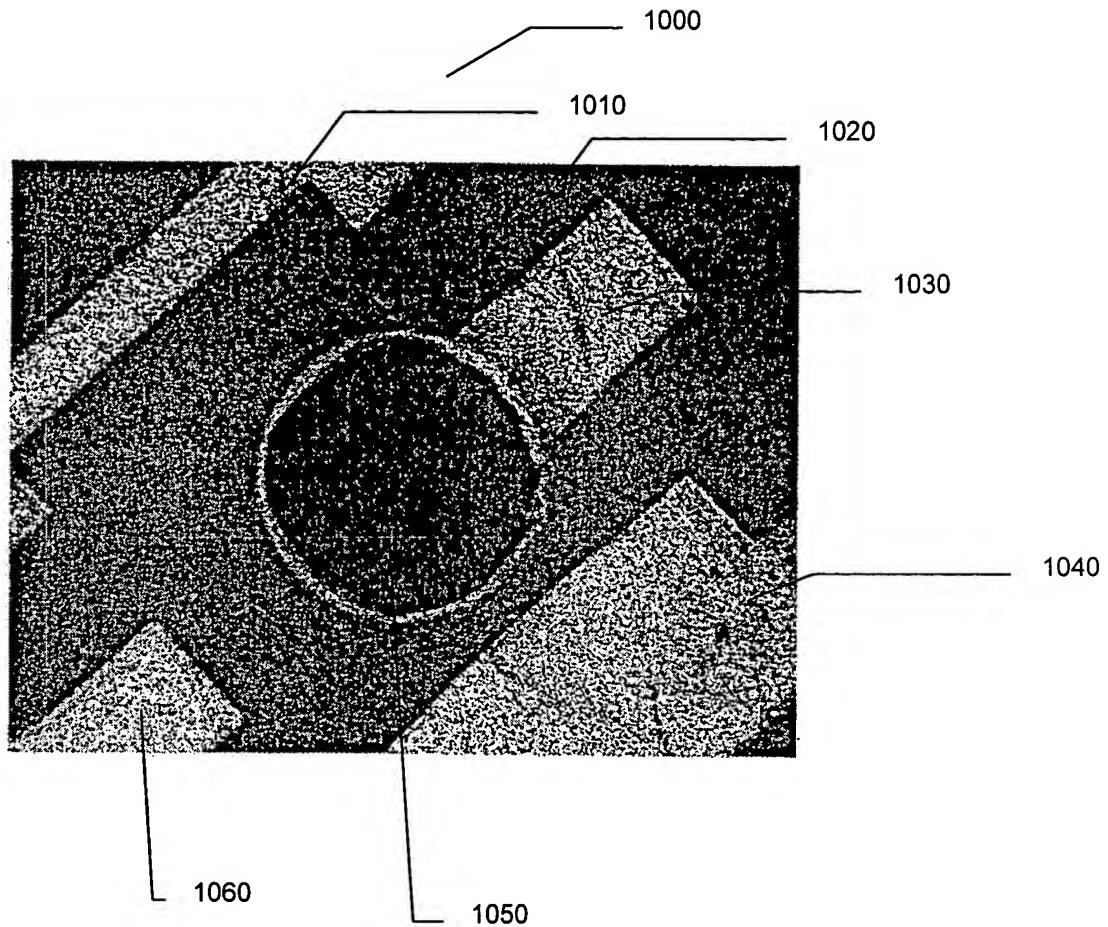


FIGURE 10

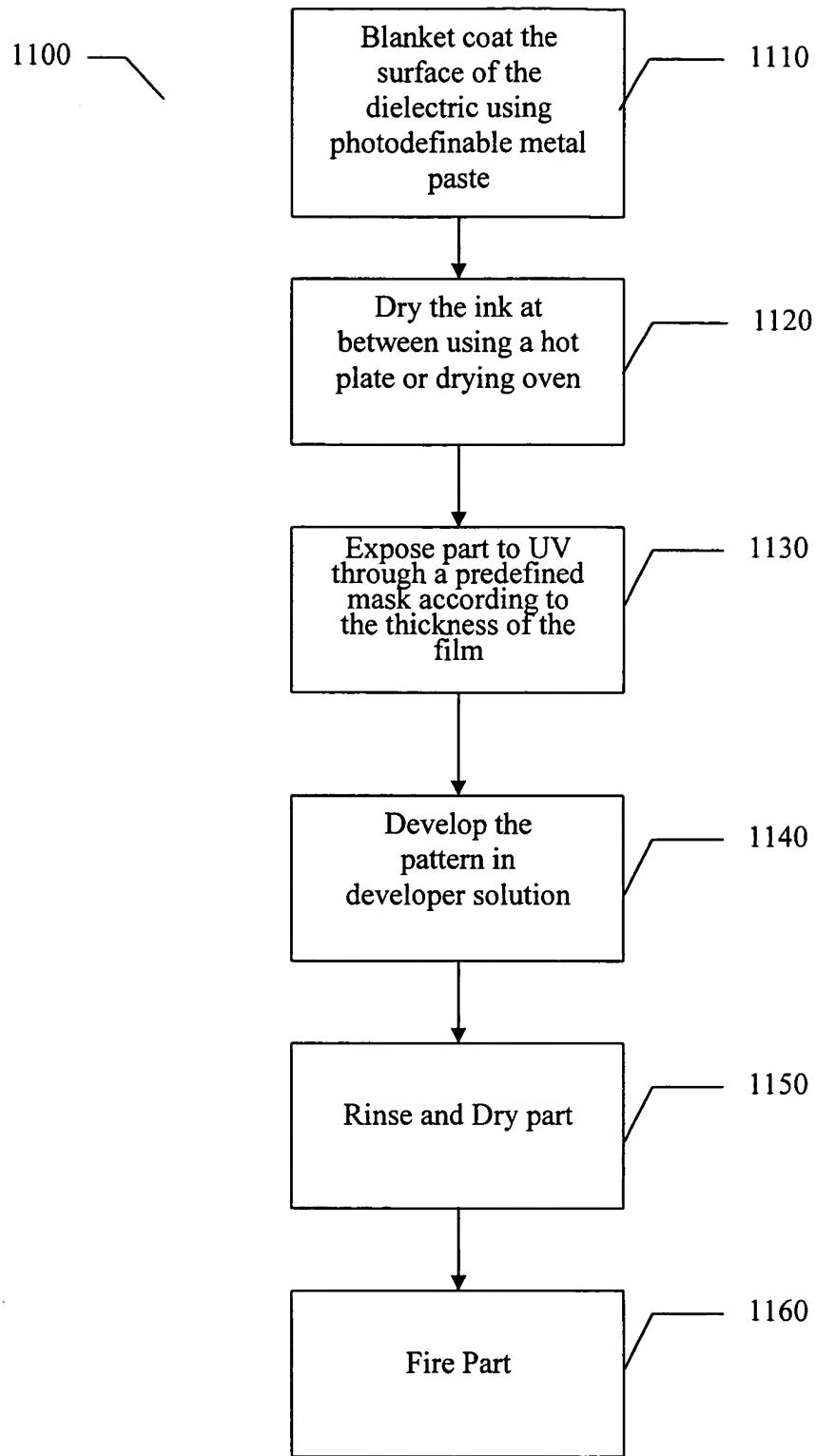


FIGURE 11

Process Steps	Photo-Define	Screen-Print	Etching	Typical Semiconductor patterning	Laser Patterning
Apply wet metal	Yes	Yes	Yes	No	Yes
Drying of metal/photoresist	Yes	Yes	Yes	Yes	Yes
Exposing of metal or photoresist	Yes	No	Yes	Yes	No
Developing of metal or photoresist	Yes	Yes	Yes	Yes	No
Firing of Metal	Yes	Yes	Yes	No	Yes
Further trimming to obtain correct dimensions (not RF trimming)	No	Yes limited in dimensions	No	No	Limited to laser spot size
Vacuum Metallization (limited in deposition thicknesses)	No	No	No	Yes	No
Chemical Etching	No	No	Yes	Yes	No
Post Annealing/Cleaning	No	Yes	Yes	Yes	Yes

FIGURE 12